S/N 10/602,323

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:

Kie Y. Ahn et al.

Examiner:

Fernando L Toledo

Serial No.:

10/602,323

Group Art Unit:

2823

Filed:

June 24, 2003

Docket:

1303.101US1

Title:

LANTHANIDE OXIDE / HAFNIUM OXIDE DIELECTRIC LAYERS

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Amendment Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 et. seq., the enclosed materials are brought to the attention of the Examiner for consideration in connection with the above-identified patent application. Applicants respectfully request that this Supplemental Information Disclosure Statement be entered and the documents listed on the attached Form 1449 be considered by the Examiner and made of record. Pursuant to the provisions of MPEP 609, Applicants request that a copy of the 1449 form, initialed as being considered by the Examiner, be returned to the Applicants with the next official communication.

Pursuant to 37 C.F.R. §1.97(c)(2), Applicants have included the fee of \$180.00 as set forth in 37 C.F.R. §1.17(p). Please charge any additional fees or credit any overpayment to Deposit Account No. 19-0743.

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Serial No :10/602,323 Filing Date: June 24, 2003

Title: LANTHANIDE OXIDE / HAFNIUM OXIDE DIELECTRIC LAYERS

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The Examiner is invited to contact the Applicants' Representative at the below-listed telephone number if there are any questions regarding this communication.

Pursuant to 37 C.F.R. 1.98(a)(2), Applicant believes that copies of cited U.S. Patents and Published Applications are no longer required to be provided to the Office. Notification of this change was provided in the United States Patent and Trademark Office OG Notices dated October 12, 2004. Thus, Applicant has not included copies of any US Patents or Published Applications cited with this submission. Should the Office require copies to be provided, Applicant respectfully requests that notice of such requirement be directed to Applicant's below-signed representative. Applicant acknowledges the requirement to submit copies of foreign patent documents and non-patent literature in accordance with 37 C.F.R. 1.98(a)(2).

Respectfully submitted,

KIE Y. AHN ET AL.

By their Representatives,

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Date O September 2005

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CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: MS Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this day of September, 2005.

Nama

Signature Lacia Loo

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Complete if Known Substitute for form 1449A/PTO INFORMATION DISCLOSURE **Application Number** 10/602,323 STATEMENT BY APPLICANT **Filing Date** June 24, 2003 **First Named Inventor** Ahn, Kie **Group Art Unit** 2823 Toledo, Fernando **Examiner Name** Attorney Docket No: 1303.101US1 Sheet 1 of 3

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**EXAMINER** 

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US Patent & Tradement Office: U.S. DEPARTMENT OF COMMERCE
Under the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it contains a valid OMB control number. Substitute for form 1449A/PTO Complete if Known INFORMATION DISCLOSURE **Application Number** 10/602,323 STATEMENT BY APPLICANT (Use as many sheets as necessary) **Filing Date** June 24, 2003 **First Named Inventor** Ahn, Kie **Group Art Unit** 2823 **Examiner Name** Toledo, Fernando Attorney Docket No: 1303.101US1 Sheet 2 of 3

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	OTHE	R DOCUMENTS NON PATENT LITERATURE DOCUMENTS	
Examiner Initials*	Cite No 1	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T²
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**EXAMINER** 

**DATE CONSIDERED** 

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Index the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it contains a valid OMB control number. Substitute for form 1449A/PTO Complete if Known INFORMATION DISCLOSURE 10/602,323 **Application Number** STATEMENT BY APPLICANT June 24, 2003 (Use as many sheets as necessary) **Filing Date First Named Inventor** Ahn, Kie **Group Art Unit** 2823 **Examiner Name** Toledo, Fernando Attorney Docket No: 1303.101US1 Sheet 3 of 3

	OTHE	R DOCUMENTS NON PATENT LITERATURE DOCUMENTS	
Examiner Initials*	Cite No <sup>1</sup>	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T <sup>2</sup>
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**EXAMINER** 

<u>S/N 10/602,323</u> <u>PATENT</u>

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Kie Y. Ahn et al. Examiner: Fernando L. Toledo

 Serial No.:
 10/602,323
 Group Art Unit: 2823

 Filed:
 June 24, 2003
 Docket: 1303.101US1

Title: LANTHANIDE OXIDE / HAFNIUM OXIDE DIELECTRIC LAYERS

## **COMMUNICATION CONCERNING RELATED APPLICATION(S)**

Mail Stop Amendment Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Applicants would like to bring to the Examiner's attention the following related application(s) in the above-identified patent application:

Serial/Patent No.	Filing Date/Issue Date August 29, 2005	Attorney Docket 1303.048US2	Title SYSTEMS AND APPARATUS FOR ATOMIC-LAYER DEPOSITION
11/092072	March 29, 2005	1303.135US1	ALD OF AMORPHOUS LANTHANIDE DOPED TIOX FILMS
11/093104	March 29, 2005	1303.136US1	ATOMIC LAYER DEPOSITED TITANIUM SILICON OXIDE FILMS
11/117121	April 28, 2005	1303.138US1	ATOMIC LAYER DEPOSITED ZIRCONIUM SILICON OXIDE FILMS
11/117125	April 28, 2005	1303.139US1	ATOMIC LAYER DEPOSITION OF A RUTHENIUM LAYER TO A LANTHANIDE OXIDE DIELECTRIC LAYER
11/084968	March 21, 2005	1303.083US2	Zr-Sn-Ti-O FILMS
11/148505	June 9, 2005	1303.061US2	ATOMIC LAYER DEPOSITED NANOLAMINATES OF Hf02/ZrO2 FILMS AS GATE DIELECTRICS
11/178914	July 11, 2005	1303.061US3	NANOLAMINATES OF HAFNIUM OXIDE AND ZIRCONIUM OXIDE
11/189075	July 25, 2005	1303.148US1	MAGNESIUM TITANIUM OXIDE FILMS
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	August 26, 2005	1303.090US2	ATOMIC LAYER DEPOSITED DIELECTRIC LAYERS

## COMMUNICATION CONCERNING RELATED APPLICATIONS

Serial Number: 10/602,323 Filing Date: June 24, 2003

Title: LANTHANIDE OXIDE / HAFNIUM OXIDE DIELECTRIC LAYERS

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	August 26, 2005	1303.097US2	ATOMIC LAYER DEPOSITED ZIRCONIUM TITANIUM OXIDE FILMS
11/204745	August 16, 2005	1303.044US3	EVAPORATION OF Y-Si-O FILMS FOR MEDIUM-k DIELETRICS
	August 29, 2005	1303.082US3	ATOMIC LAYER DEPOSITED Zr-Sn-Ti- O FILMS USING TiI4

Continuations and divisionals may be later filed on the cases listed above, or cited to the Examiner in any previous Communication Concerning Related Applications. Applicants request that the Examiner review all continuations and divisionals of the above-listed or previously-cited patent applications before allowing the claims of the present patent application.

Respectfully submitted,

KIE Y. AHN ET AL.

By Applicants' Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A. P.O. Box 2938
Minneapolis, MN 55402
(612) 371-2157

Date 6 September 2005 By

David R. Cochrar Reg. No. 46,632

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Nomo

Signatur